

# Velox™ 3.3 Highlights

## Probe Station Control Software

Velox 3.3 is the next big step in improving our probe station software for greater usability. The new Wafer Map comes with a modernized user interface and unique patented functions that make workflows more intuitive and logical. SubDie handling has been simplified in cooperation with some of our key customers. Additionally, the Velox Help has been completely re-designed for more intuitive navigation and problem-solving.

**A free upgrade is available for existing customers.\***

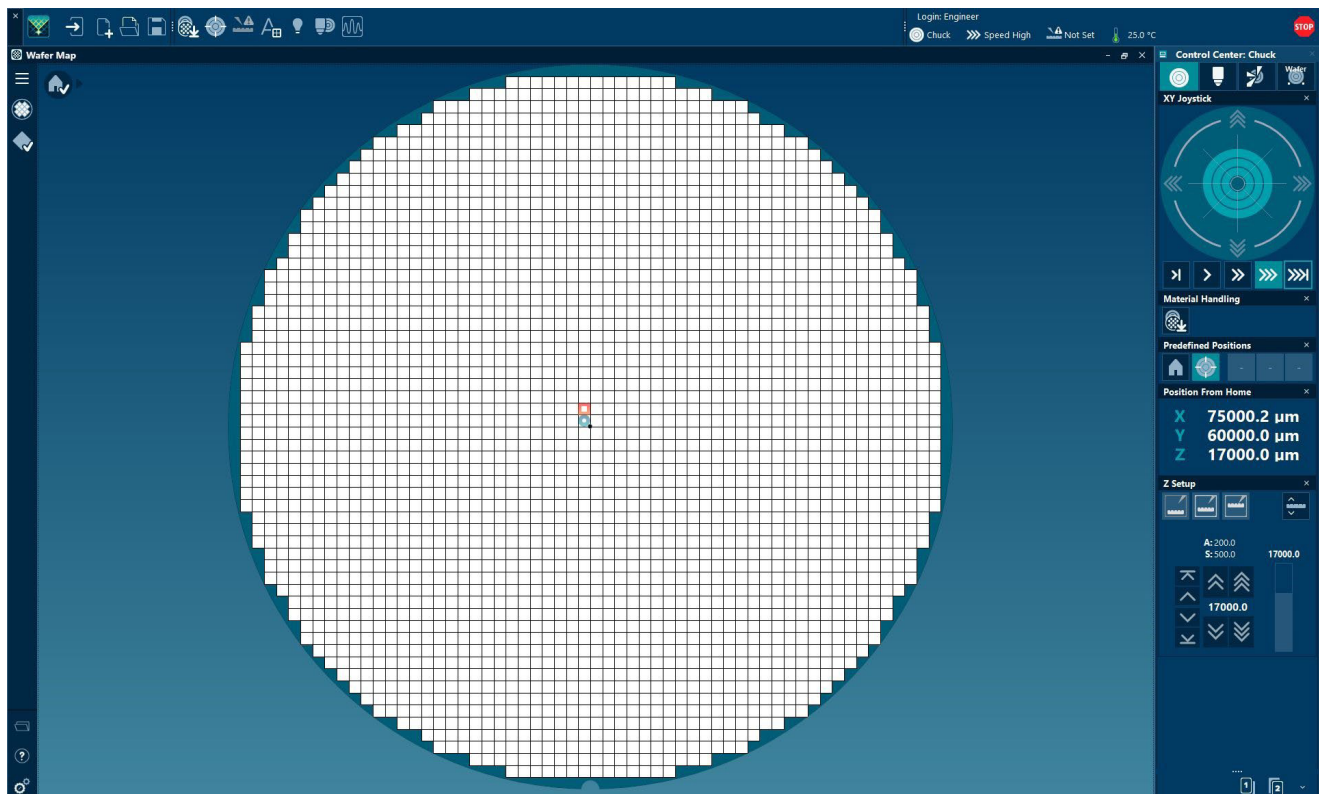


## New Wafer Map

- / New modern and intuitive user interface
- / **Floating action buttons** for faster access to most important functions like *Step Next Die* and *Set Home*
- / Logical, simplified **workflows**
- / Patented selective **Die Soaking** and **Die Alignment**
- / Optimized **SubDie handling**
- / **Z-profiling** has been simplified and is now integrated in Wafer Map
- / Support of **SEMI G85** wafer map files

### Benefit:

Intuitive, ergonomic operation with significantly less training needs.



### Die Soaking

Fixed  0 h 20 min 0 s  
 Dynamic  0 h 5 min 5 s

Use Selective Die Soaking

Die Selection Mode ?

Invert Selected Dies  
 Add Selected Dies  
 Remove Selected Dies

Die Soaking Border Area (mm)   
 Soak Every N<sup>th</sup> Center Die   
 Auto-Mark Dies

Dies for soaking: 20  
 Dies for probing: 52  
 Soak time savings at 80 °C: 9587 Minutes

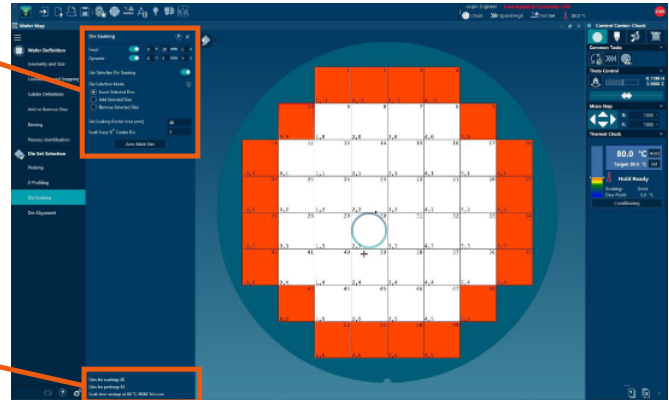
## Selective Die Soaking



- / New level of wafer testing efficiency for non-ambient probing
- / User can define soak times for each die
- / Easy-to-use graphical interface

### Benefit:

Significantly faster time to data through smarter automation.



### Die Alignment

Use Vision Assisted Stepping   
 XYZ Theta alignment using eVue/Scope.

Train Alignment Tool

Use Selective Die Alignment

Die Selection Mode ?

Invert Selected Dies  
 Add Selected Dies  
 Remove Selected Dies

Align Every N<sup>th</sup> Die   
 Mark Every N<sup>th</sup> Die

Dies for alignment: 26  
 Dies for probing: 52

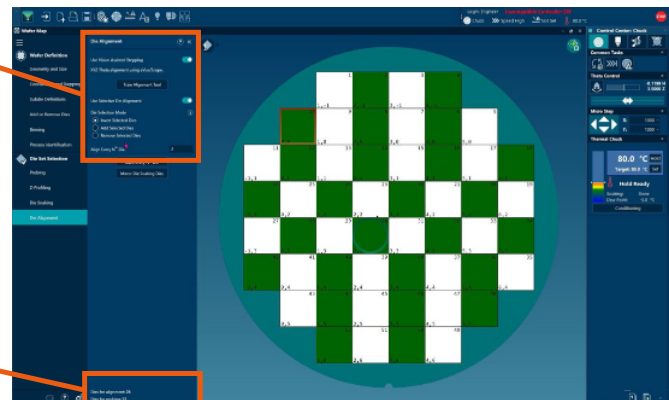
## Selective Die Alignment

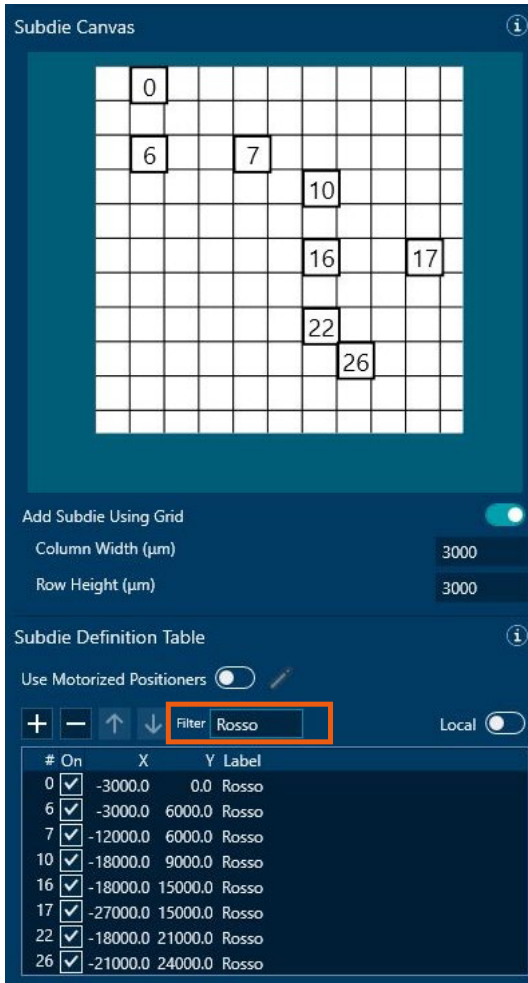


- / User can define which dies need alignment
- / No complex adaptations of the Test Executive necessary

### Benefit:

Significantly faster time to data through smarter automation.

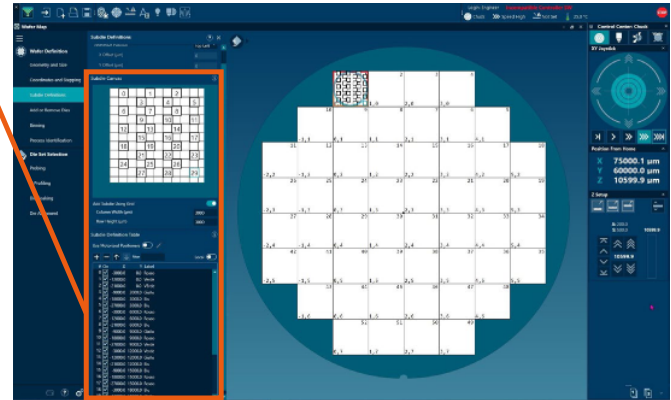




## Sub Die Handling

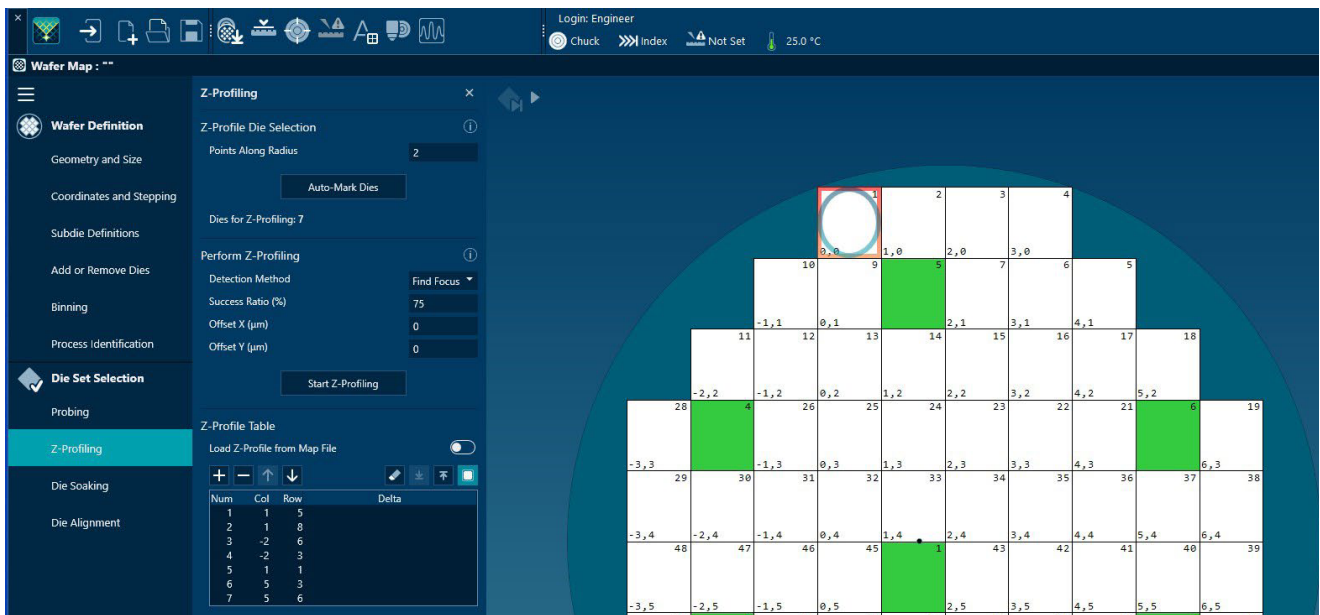
- / Sub Dies can be labeled with different colors for better differentiation
- / Drag/drop Sub Dies to different positions in table
- / Select multiple Sub Dies in table
- / Filter by labels

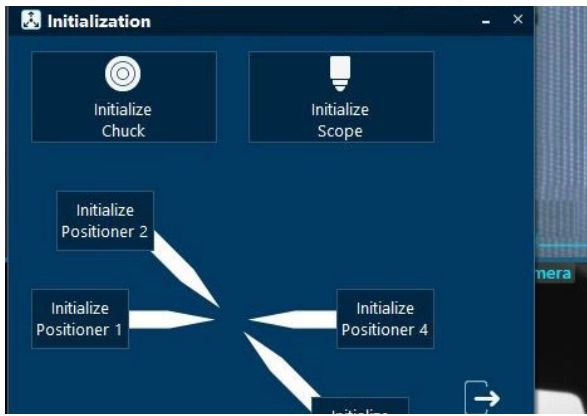
**Benefit:**  
Easier handling of multiple Sub Dies.



## Z-Profiling

- / Z-Profiling tool integrated in Wafer Map
- / No additional application necessary





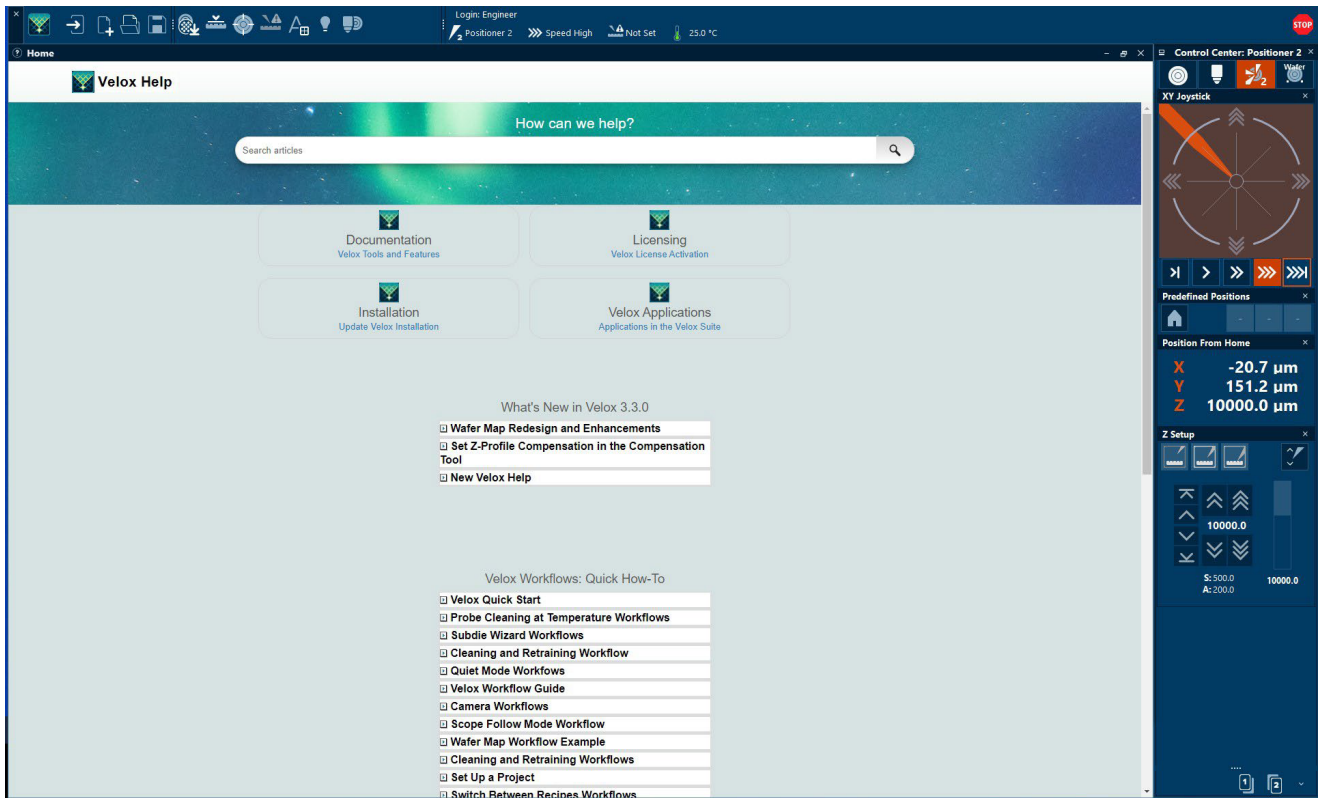
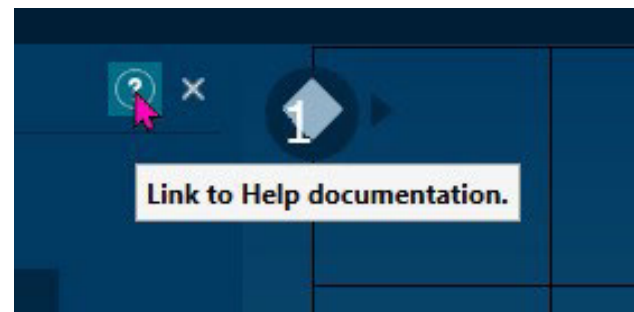
## Initialization Tool

- / Calibration of chuck stage, microscope stage and motorized positioners
- / Can be done by the user, no FormFactor service needed
- / Self-explaining user interface

**Benefit:**  
Less training needed. Faster setup times.

## New Velox Help

- / Velox Help has been re-designed to provide easier access
- / Improved search function
- / Access help directly from Velox
- / Workflows, Quick How-To, Frequently Asked Questions and more



\* Requires Service visit. Please contact your local sales person for more information.